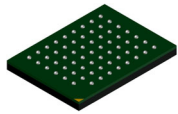
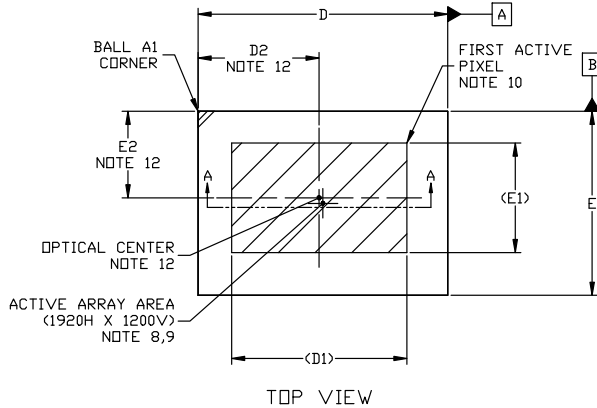


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



ODCSP62 7.66x5.64x0.44, 0.70P
CASE 570CY
ISSUE A

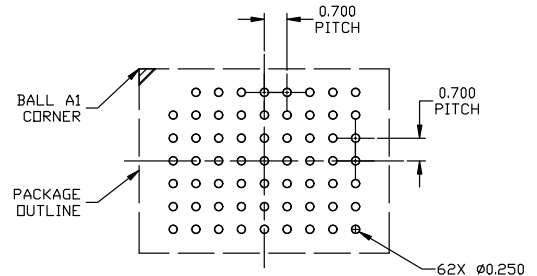
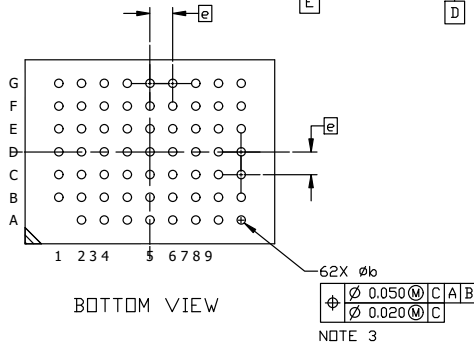
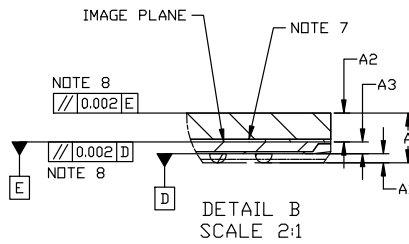
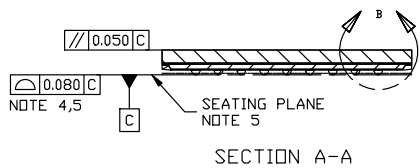
DATE 30 AUG 2023



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.044 THICKNESS.
8. PARALLELISM APPLIES ON TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUM A AND B IS $\pm 0.1^\circ$.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER(X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.114, 0.170).

DIM	MILLIMETERS		
	MIN.	NOM.	MAX
A	----	----	0.781
A1	0.110	0.140	0.170
A2	0.424	0.444	0.464
A3	0.160	0.180	0.200
b	0.220	0.250	0.280
D	7.639	7.664	7.689
D1	5.376 REF.		
D2	3.693	3.718	3.743
E	5.623	5.648	5.673
E1	3.360 REF.		
E2	2.629	2.654	2.679
e	0.700 BSC		



RECOMMENDED MOUNTING FOOTPRINT*
*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	ODCSP62 7.66x5.64x0.44, 0.70P	PAGE 1 OF 1

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